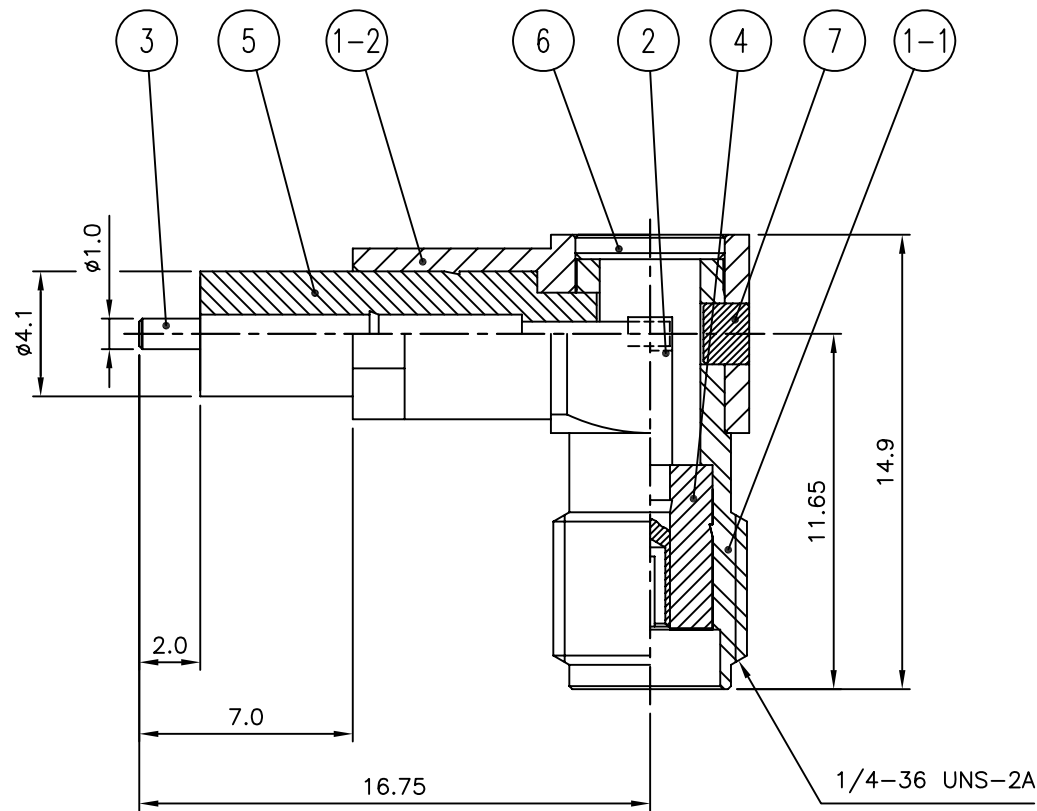
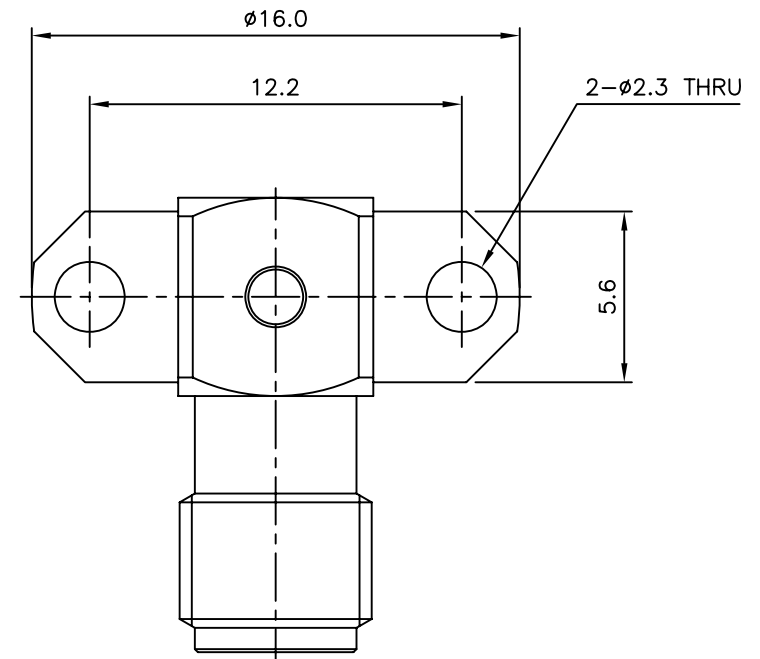




REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	C.K.KIM	I.C.KIM	2016.08.30.



조립순서

1. ①번(A+B) BODY에 ⑦번 KEY를 조립한다.
2. ④번 TEFLON에 ②번 PIN을 조립한다.
3. ⑤번 TEFLON에 ③번 PIN을 조립한다.
4. ④+②번을 1-1(A) BODY에 조립한다.
5. ⑤+③번을 1-2(B) BODY에 조립한다.
6. ②번, ③번 PIN을 SOLDER 한다.
7. ⑥번 COVER을 조립한다.

* 커플링 토크 관리규격 0.9~1.1N·m

7	KEY	1	MBsBD C3604BD-F	Nickel Plate	DKY00024-5/1
6	COVER	1	MBsBD C3604BD-F	Nickel Plate	DCO00023-5/2
5	INSULATOR	1	TEFLON		DIN02830-N/1
4	INSULATOR	1	TEFLON		DIN01973-N/1
3	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT03757-5/1
2	CONTACT	1	BeCu C17300	Gold Plate	DCT03756-5/1
1	1-2 BODY(B)	1	MBsBD C3604BD-F	Nickel Plate	DBB00450-5/2
	1-1 BODY(A)	1	MBsBD C3604BD-F	Nickel Plate	DBD04225-1/2 DBD04226-3/1
NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal	DATE 2016. 08. 30.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017
	Angle	APPROVED BY	I.C.KIM	
MATERIAL		CHECKED BY		KJ COMTECH CO., LTD. TITLE SMA50 SOLDER END JL-2H
		DRAWN BY	C.K.KIM	
FINISH		SCALE	4/1	A4 DWG NO. CN03643-7/2 REVISION I R SHEET 1 of 1
		UNIT	mm	